

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Lup San LEONG	03/06/2008
Yong Kong SIEW	03/12/2008
Liang Choo HSIA	03/12/2008
RECEIVING PARTY DATA	
Name:	Chartered Semiconductor Manufacturing, Ltd.
Street Address:	60 Woodlands Industrial Park D Street 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	738406
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12048223
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	CSM P 2007 NAT 112 US 0
NAME OF SUBMITTER:	Dexter CHIN
<p>Total Attachments: 4</p> <p>source=CSMP2007NAT112US0-Assignment#page1.tif</p> <p>source=CSMP2007NAT112US0-Assignment#page2.tif</p>	

CH \$40.00 12048223

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PATENT
REEL: 020649 FRAME: 0533

ASSIGNMENT

For good and valuable consideration, we, Lup San LEONG, residing at Blk 274, Choa Chu Kang Ave 2, #10-231, Singapore 680274, a citizen of Singapore; Yong Kong SIEW, residing at 2 Taman Berjaya, Sungai Pelek, Selangor, Malaysia, a citizen of Malaysia; Liang Choo HSIA, residing at 22 Woodgrove Avenue, Singapore 738064, a citizen of the United States of America;

Hereby sell, assign, and transfer to **Chartered Semiconductor Manufacturing, Ltd.**, a corporation of **Singapore**, having its principal place of business at **60 Woodlands Industrial Park D Street 2, Singapore 738406**,

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently here within, and is entitled:

INTERCONNECTIONS FOR INTEGRATED CIRCUITS

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do

everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:

6 Mar 2008.



(Signature)

Lup San **LEONG**

Witness 1:



(Signature)

YAP POH PENG.

(Print name)

Witness 2:



(Signature)

Lin Benfu


(Print name)

Date: 12 Mar 08




(Signature)

Yong Kong SIEW

Witness 1: 
(Signature)

YAP POH PENG
(Print name)


Witness 2: 
(Signature)

Lin Benfu
(Print name)

Date: 12 Mar 08


(Signature)
Liang Choo HSLA

Witness 1: Ym.
(Signature)
YAP POH PENG
(Print name)

Witness 2: 
(Signature)
LIN Benfu
(Print name)